



# Final Product/Process Change Notification

Document #:FPCN24010X

Issue Date:08 Nov 2021

<b>Title of Change:</b>	Package assembly site transfer for narrow body SOIC packages from Amkor and/ or ASE Chung Li to ASE Kunshan
<b>Proposed First Ship date:</b>	15 Feb 2022 or earlier if approved by customer
<b>Contact Information:</b>	Contact your local onsemi Sales Office or Lay Woon Lim < <a href="mailto:LayWoon.Lim@onsemi.com">LayWoon.Lim@onsemi.com</a> >.
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office or < <a href="mailto:PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>Additional Reliability Data:</b>	Contact your local onsemi Sales Office or <a href="mailto:Phine.Guevarra@onsemi.com">Phine.Guevarra@onsemi.com</a>
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>
<b>Marking of Parts/ Traceability of Change:</b>	Parts can be identified by the assembly code in the traceability code
<b>Change Category:</b>	Assembly Change
<b>Change Sub-Category(s):</b>	Manufacturing Site Transfer, Material Change

**Sites Affected:**

onsemi Sites	External Foundry/Subcon Sites
None	ASECL, Taiwan (ChungLi)
	ASEKS, China
	ATP1 - Amkor Technology Philippines P1

**Description and Purpose:**

This Final PCN is to notify of the completed actions to qualify a new package assembly site, ASE located in Kunshan, China (ASEKS) for narrow body SOIC-8 and SOIC-16 packages that are currently assembled in Amkor Tech Philippines Plant 1 and/ or ASE in Chung Li. This change is to allow onsemi to consolidate the package assembly manufacturing of SOIC packages to limited sites for better supply chain management and manufacturing flexibility. The package BOM will be changed to the standard BOM for the SOIC packages at ASEKS. Due to specific tooling requirement at ASEKS, a few minor physical dimension parameters on the case outline drawing or physical outline drawing will be changing as detailed below.

	Before Change Description	After Change Description
Assembly Site	Amkor Tech Philippines Plant 1 ASE Chung Li	ASE Kunshan
Die Attach	Henkel EPOXY 8290, EPOXY 84-1 LMIS R4 Hitachi EN4900G	Hitachi EN4900GC
Mold Compound	Sumitomo EME-6600H, EME-G600, G700LS Sumitomo G700LY	Hitachi CEL-9240HF10AK

	From	To
Product marking change	Assembly Site Code for Amkor or ASE Chung Li	Latest marking style format. Assembly Site Code for ASEKS.

	From	To															
<p><b>Case Outline Drawing Changes</b></p> <p>SOIC-8 Case Outline # 751AZ Document # 98AON34918E SOIC-16 Case Outline # 751BA Document # 98AON34919E</p>	<table border="1"> <thead> <tr> <th colspan="3">case outline 751AZ (mm)</th> </tr> <tr> <th>DIM</th> <th>MIN</th> <th>MAX</th> </tr> </thead> <tbody> <tr> <td>h</td> <td>0.25</td> <td>0.41</td> </tr> </tbody> </table>	case outline 751AZ (mm)			DIM	MIN	MAX	h	0.25	0.41	<table border="1"> <thead> <tr> <th>DIM</th> <th>MIN</th> <th>MAX</th> </tr> </thead> <tbody> <tr> <td>h</td> <td>0.25</td> <td>0.50</td> </tr> </tbody> </table>	DIM	MIN	MAX	h	0.25	0.50
case outline 751AZ (mm)																	
DIM	MIN	MAX															
h	0.25	0.41															
DIM	MIN	MAX															
h	0.25	0.50															

**Reliability Data Summary:**

**QV DEVICE NAME: QV1**

**RMS: O78780**

**PACKAGE: SOIC-8**

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
TC+PC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/231
UHAST+PC	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 2 @ 260 °C		0/462
SD	JSTD002	Ta = 245C, 10 sec		0/45
PD	JESD22-B100 and JESD22-B108	Per Case Outline		0/30

**QV DEVICE NAME: FS6370-01G-XTD**

**RMS: O78781; O80724**

**PACKAGE: SOIC-16**

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
TC+PC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/231
UHAST+PC	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 2 @ 260 °C		0/462
SD	JSTD002	Ta = 245C, 10 sec		0/45
PD	JESD22-B100 and JESD22-B108	Per Case Outline		0/30

**QV DEVICE NAME: FS7140-01G-XTD**

**RMS: O78782**

**PACKAGE: SOIC-16**

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
TC+PC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/231
UHAST+PC	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 2 @ 260 °C		0/462
SD	JSTD002	Ta = 245C, 10 sec		0/45
PD	JESD22-B100 and JESD22-B108	Per Case Outline		0/30



## Final Product/Process Change Notification

Document #:FPCN24010X

Issue Date:08 Nov 2021

### Electrical Characteristics Summary:

Electrical characteristics are not impacted.

### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FS7140-01G-XTP	FS7140-01G-XTD
FS7140-01G-XTD	FS7140-01G-XTD
FS6377-01IG-XTD	FS6370-01G-XTD
FS6377-01G-XTP	FS6370-01G-XTD
FS6377-01G-XTD	FS6370-01G-XTD

---

**Appendix A: Changed Products****PCN#: FPCN24010X**  
**Issue Date: Nov 08, 2021**

---

---

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FS7140-01G-XTD	13715-806-XTD	FS7140-01G-XTD	NA	
FS6377-01G-XTD	11486-912-XTD	FS6370-01G-XTD	NA	
FS6377-01IG-XTD	11486-913-XTD	FS6370-01G-XTD	NA	